



PATENT APPLICATION

#1312
4/25/03

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of

Kazunori SAKURAI et al.

Group Art Unit: 2824

Application No.: 09/843,924

Examiner: Michael K. Luhrs

Filed: April 30, 2001

Docket No.: 109182

For: METHOD FOR FORMING BUMP, SEMICONDUCTOR DEVICE AND METHOD
FOR MAKING THE SAME, CIRCUIT BOARD, AND ELECTRONIC DEVICE

SECOND SUPPLEMENTAL AMENDMENT

Director of the U.S. Patent and Trademark Office
Washington, D.C. 20231

Sir:

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APR 21 2003
TECHNOLOGY CENTER 2800

As supplement to the Supplemental Amendment filed April 11, 2003, please further
amend the above-identified application as follows:

IN THE CLAIMS:

Please replace claim 1:

1. (Twice Amended) A method for forming a bump, comprising:
- forming a resist layer that defines a through hole which overlaps at least a portion of a pad;
 - forming an opening in an insulating film after forming the resist layer, the opening exposing at least a part of the pad; and
 - forming a metal layer constituting a bump after forming the opening, the metal layer connected to the portion of the pad exposed at the opening.